



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP742T		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000975734						
<b>Package</b>		PG-DSO-8-24		<b>Weight*</b>		82.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.250	1.51	1.51	15065	15065
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.717	0.86		8645	
wire	non noble metal	copper	7440-50-8	29.121	35.10	36.01	351026	360211
	noble metal	gold	7440-57-5	0.281	0.34	0.34	3388	3388
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
plastics	plastics	epoxy resin	-	4.565	5.50		55025	
	inorganic material	silicondioxide	60676-86-0	44.954	54.20	59.82	541873	598093
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9810	9810
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7838	7838
glue	plastics	epoxy resin	-	0.081	0.10		979	
	noble metal	silver	7440-22-4	0.383	0.46	0.56	4615	5594
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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